Vishay Semiconductors

High Speed Infrared Emitting Diodes, 940 nm, Surface Emitter Technology



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LINKS TO ADDITIONAL RESOURCES



DESCRIPTION

As part of the <u>SurfLight</u>^{IM} portfolio, the VSMY2940 series are infrared, 940 nm emitting diodes based on GaAlAs surface emitter chip technology with extreme high radiant intensities, high optical power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

FEATURES

- Package type: surface-mount
- Package form: GW, RGW
- Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.8
- Peak wavelength: $\lambda_p = 940 \text{ nm}$
- AEC-Q101 qualified
- · High radiant power
- · Very high radiant intensity
- Angle of half intensity: $\phi = \pm 10^{\circ}$
- Suitable for high pulse current operation
- Terminal configurations: gullwing or reverse gullwing
- Package matches with detector VEMD2000X01 series
- Floor life: 4 weeks, MSL 2a, according to J-STD-020
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Miniature light barrier
- Photointerrupters
- Optical switch
- Emitter source for proximity sensors
- Head-up displays

PRODUCT SUMMARY					
COMPONENT	l _e (mW/sr)	φ (°)	λ _P (nm)	t _r (ns)	
VSMY2940RGX01	145	± 10	940	10	
VSMY2940GX01	145	± 10	940	10	

Note

• Test conditions see table "Basic Characteristics"

ORDERING INFORMATION					
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM		
VSMY2940RGX01	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Reverse gullwing		
VSMY2940GX01	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Gullwing		

Note

• MOQ: minimum order quantity

AUTOMOTIVE GRADE



COMPLIANT HALOGEN

GREEN

(5-2008)



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ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT		
Reverse voltage		V _R	5	V		
Forward current		I _F	100	mA		
Peak forward current	$t_p/T = 0.5, t_p = 100 \ \mu s$	I _{FM}	200	mA		
Surge forward current	t _p = 100 μs	I _{FSM}	1	A		
Power dissipation		Pv	170	mW		
Junction temperature		Tj	100	°C		
Operating temperature range		T _{amb}	-40 to +85	°C		
Storage temperature range		T _{stg}	-40 to +100	°C		
Soldering temperature	According to Fig. 10, J-STD-020	T _{sd}	260	°C		
Thermal resistance junction-to-ambient	J-STD-051, soldered on PCB	R _{thJA}	250	K/W		

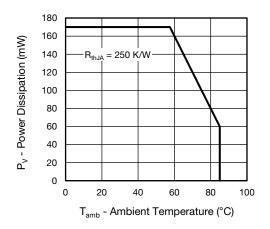


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

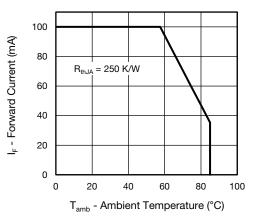


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
	I _F = 100 mA, t _p = 20 ms	V _F	-	1.4	1.8	V
Forward voltage	I _F = 1 A, t _p = 100 μs	V _F	-	2.5	-	V
Temperature coefficient of V _F	I _F = 100 mA	TK _{VF}	-	-0.7	-	mV/K
Reverse current		I _R	Not designed for reverse operation			μA
Junction capacitance	$V_{R} = 0 V, f = 1 MHz, E = 0 mW/cm^{2}$	CJ	-	55	-	pF
Radiant intensity	I _F = 100 mA, t _p = 20 ms	l _e	75	145	215	mW/sr
Radiant intensity	I _F = 1 A, t _p = 100 μs	l _e	-	1000	-	mW/sr
Radiant power	I _F = 100 mA, t _p = 20 ms	фе	-	55	-	mW
Temperature coefficient of radiant power	I _F = 100 mA	ΤΚφ _e	-	-0.2	-	%/K
Angle of half intensity		φ	-	± 10	-	0
Peak wavelength	I _F = 100 mA	λρ	920	940	960	nm
Spectral bandwidth	I _F = 100 mA	Δλ	-	50	-	nm
Temperature coefficient of λ_p	I _F = 100 mA	ΤΚλ _p	-	0.25	-	nm/K
Rise time	I _F = 100 mA, 10 % to 90 %	t _r	-	10	-	ns
Fall time	I _F = 100 mA, 10 % to 90 %	t _f	-	10	-	ns

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BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

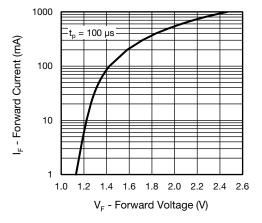


Fig. 3 - Forward Current vs. Forward Voltage

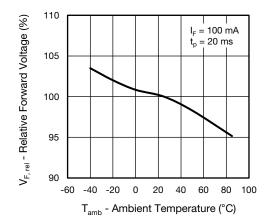


Fig. 4 - Relative Forward Voltage vs. Ambient Temperature

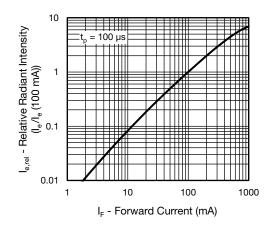


Fig. 5 - Relative Radiant Intensity vs. Forward Current

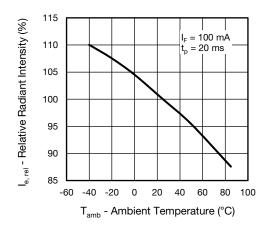


Fig. 6 - Relative Radiant Intensity vs. Ambient Temperature

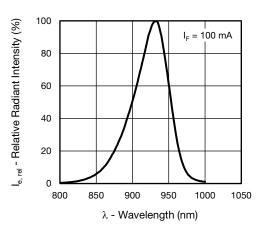


Fig. 7 - Relative Radiant Intensity vs. Wavelength

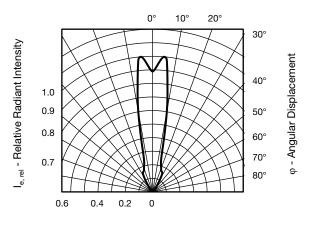


Fig. 8 - Relative Radiant Intensity vs. Angular Displacement

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Document Number: 84583

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SOLDER PROFILE

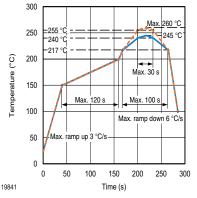


Fig. 9 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020

FLOOR LIFE

DRYPACK

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during

transportation and storage. Each bag contains a desiccant.

Floor life: 4 weeks

Conditions: T_{amb} < 30 °C, RH < 60 %

Moisture sensitivity level 2a, according to J-STD-020.

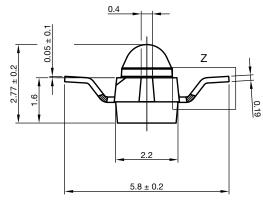
DRYING

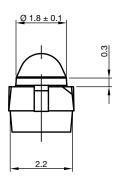
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.

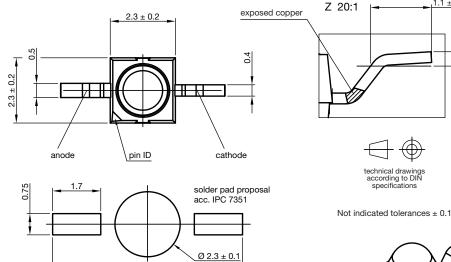
 1.1 ± 0.1

0.254

PACKAGE DIMENISONS in millimeters: VSMY2940RGX01







6.7

Drawing-No.: 6.544-5391.03-4

Issue: 2; 19.09.14

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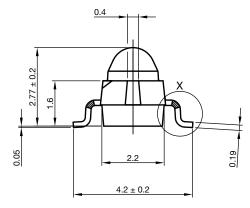
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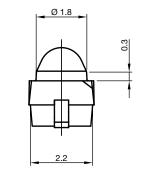
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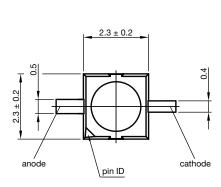
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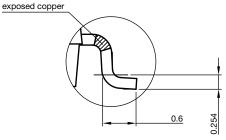
PACKAGE DIMENSIONS in millimeters: VSMY2940GX01





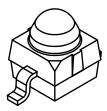
X 20:1







Not indicated tolerances ± 0.1



Drawing-No.: 6.544-5383.03-4 Issue: 2; 19.09.14

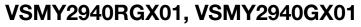
2.45 5.15

solder pad proposal acc. IPC 7351

0.75

5

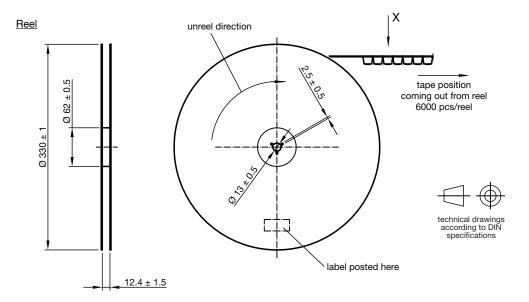
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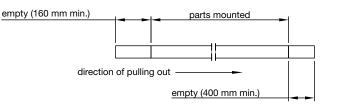
TAPING AND REEL DIMENSIONS in millimeters: VSMY2940RGX01

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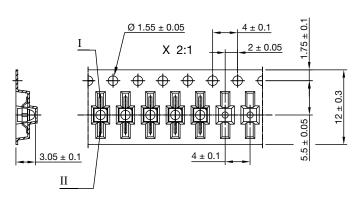
Leader and trailer tape

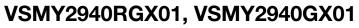
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Terminal position in tape Device Lead I Lead II VEMT2000 Collector Emitter VEMT2500 VEMD2000 VEMD2500 VSMB2000 Cathode Anode VSMG2000 VSMF2890RG VSMY2850RG Cathode Anode VSMY2940RG

Drawing-No.: 9.800-5100.01-4 Issue: 4; 19.09.14

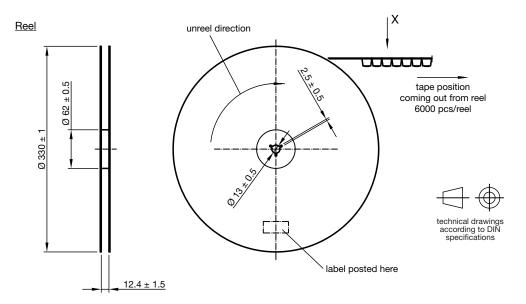




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TAPING AND REEL DIMENSIONS in millimeters: VSMY2940GX01

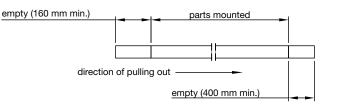
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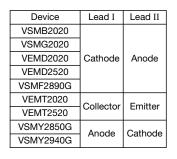


Leader and trailer tape

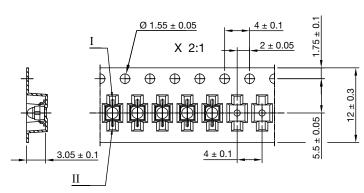
Terminal position in tape

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Drawing-No.: 9.800-5091.01-4 Issue: 5; 19.09.14





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